



# BGA Questionnaire

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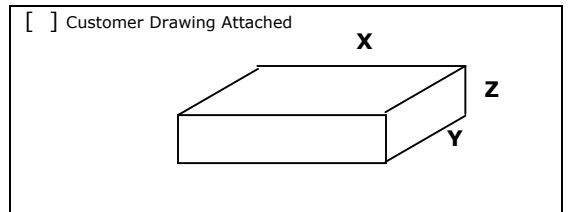
**Contact:**

Name: \_\_\_\_\_  
 Company: \_\_\_\_\_  
 Email: \_\_\_\_\_  
 Project Ref: \_\_\_\_\_

Title: \_\_\_\_\_  
 Dept: \_\_\_\_\_  
 Tel: \_\_\_\_\_ Ext \_\_\_\_\_

**Outline Size:** [ ] mm [ ]  $\mu$ m [ ] mil [ ] inch

Substrate Size (Minimum): X= Y= Z=  
 Substrate Size (Maximum): X= Y= Z=

**Substrate Material:**

[ ] BT [ ] FR4 [ ] Si [ ] Ceramic [ ] Pi [ ] Any  
 [ ] Other: \_\_\_\_\_

**Ball Pitch (mm):**

[ ] 0.3 [ ] 0.4 [ ] 0.5 [ ] 0.65 [ ] 0.75  
 [ ] 0.8 [ ] 1.0 [ ] 1.27 [ ] 1.5

**Solder Ball Alloy:****Solder Ball Diameter:**

[ ] SAC305 - Sn96.5/Ag3.0/Cu0.5	[ ] 0.20mm	[ ] 0.45mm
[ ] SnPb - Sn63/Pb37	[ ] 0.25mm	[ ] 0.50mm
[ ] Other _____	[ ] 0.30mm	[ ] 0.63mm
	[ ] 0.35mm	[ ] 0.76mm
	[ ] 0.40mm	[ ] Other

**Ball Count / Matrix**

[ ] Customer Drawing

[ ] Min Balls \_\_\_\_\_ [ ] Max Balls \_\_\_\_\_  
 [ ] Full Array [ ] Perimeter [ ] Custom  
 Matrix \_\_\_\_\_ x \_\_\_\_\_  
 Perimeter Rows Nbr: \_\_\_\_\_

**Circuit Function:**

[ ] Daisy Chain [ ] BUS [ ] Isolated Pads (No Daisy Chain)  
 [ ] Throughhole via test pads on top side  
 [ ] Any type available [ ] Other: \_\_\_\_\_

**Packaging:**

[ ] Tray [ ] Waffle Pack [ ] Tape & Reel  
 [ ] Any  
 [ ] Other \_\_\_\_\_

**Dummy Die:**

Die Size: Min \_\_\_\_\_ Max \_\_\_\_\_ [ ]  $\mu$ m [ ] mil  
 Die Thick: Min \_\_\_\_\_ Max \_\_\_\_\_ [ ]  $\mu$ m [ ] mil  
 [ ] Die not required [ ] Any type available

**Mounting of Die:**  
 [ ] External (Flip Chip Style) [ ] Encapsulate (Internal)  
 [ ] Any type available

**Pad Information:**

**Size:** Min: \_\_\_\_\_ Max: \_\_\_\_\_ [ ]  $\mu$ m [ ] mil  
**Plating:** [ ] Ni-Au [ ] OSP [ ] Other:  
 [ ] Solder Mask Defined Pad  
 [ ] Non-Solder Mask Defined Pad  
 [ ] Other

**Solder Mask:**

[ ] Taiyo Model \_\_\_\_\_ [ ] Any  
 [ ] Other

**Part Number Series:**

[ ] BGA [ ] PBGA [ ] LBGA  
 [ ] CBGA [ ] WLP [ ] SBGA  
 [ ] FBGA [ ] Any Type Available  
 [ ] Other: